

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.17	100.0	3.3
			Subtotal	0.17	100	3.3
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.41	100.0	27
			Subtotal	1.41	100	27
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.03	0.04	0.53
	Copper alloy	Iron (Fe)	7439-89-6	0.07	0.1	1.32
	Copper alloy	Copper (Cu)	7440-50-8	68.83	99.86	1321.85
			Subtotal	68.93	100	1323.7
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.55	8.7	48.94
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.69	16.0	90
	Filler	Silica fused	60676-86-0	21.97	75.0	421.88
	Carbon Black	Carbon black	1333-86-4	0.09	0.3	1.69
			Subtotal	29.3	100	562.51
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.07	100.0	1.4
			Subtotal	0.07	100	1.4
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.01	5.0	0.12
	Lead alloy	Silver (Ag)	7440-22-4	0	2.5	0.06
	Lead alloy	Lead (Pb)	7439-92-1	0.12	92.5	2.31
			Subtotal	0.13	100	2.49
			Total	100.01	100	1920.4

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